

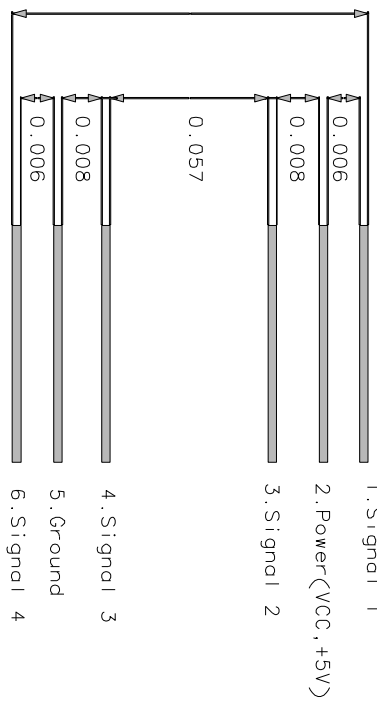
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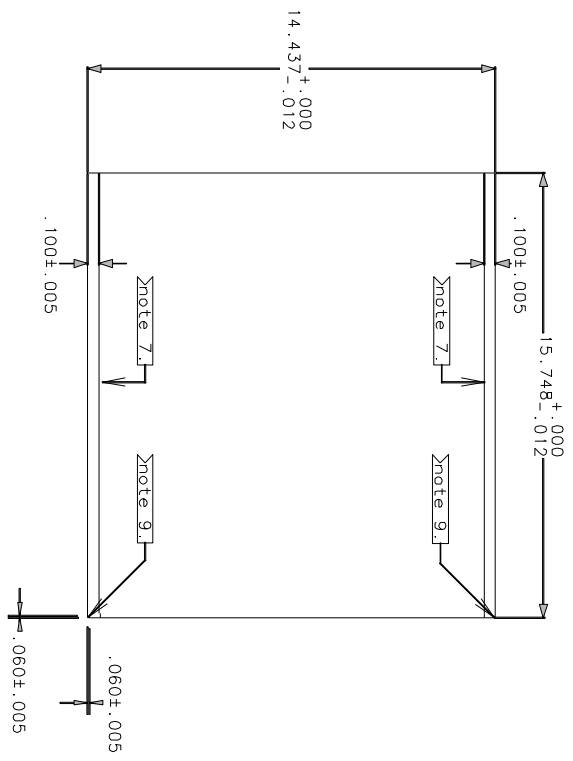
DRG. NO. B - 2460 SH. 1 REV. A

1

Layer Order



Board Thickness
0.093 +/- 0.008



BOARD'S DRILL SCHEDULE (Inches)

SYMBOL	FHS	COUNT	PLATED	TOLERANCE	COMMENT
○	.02	2511	YES	---	
⊖	.033	312	YES	---	
⊘	.035	924	YES	---	
⊖	.041	488	YES	---	
⊖	.052	2	YES	---	
⊖	.057	6	YES	---	
⊖	.09	12	NO	---	
□	.106	33	NO	---	
	.113	12	NO	---	

- Board Characteristics :
- All dimensions are given in inches unless specified otherwise.
 - Material: FR4, Tg>170C.
 - Minimum Trace Width 0.008" on all layers.
 - Minimum Clearance 0.007" on all layers.
 - 1 oz copper for all Trace and Power Layers.
 - Apply Solder and Solder Mask over bare copper.
 - Board Thickness: 0.093 +/- 0.008".
 - Mill the Top and Bottom 0.1" of board.
 - on the solder side to a thickness of 0.062" +/- 0.008".
 - Silkscreen on Component and Solder Sides.
 - 45 degree chamfer.
 - Hole diameter tolerances : +/- 0.003" unless specified otherwise.
 - Inter-layer spacing : as specified.
 - Impedance : 55 Ohm +/- 5 Ohm for signal traces on all layers.
 - Perform TDR test and present test results.

A

B

C

D

A

B

C

D

THIS SHEET IS COMPUTER GENERATED

4

3

2

1

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES FRACTIONS ARE IN INCHES DECIMALS ARE IN INCHES		CONTRACT NO.		ENRICO FERMI INST. UNIV. OF CHICAGO ELECTRONICS DEVELOPMENT GROUP	
FINISH	DO NOT SCALE DIMENSIONS	APPROVALS	DATE	TITLE	CDP L2 Final board Specification Drawing
STANDARD TO	ACI MI CALC MI	PREPARED BY THEODORE W. Bogdon	3/23/04	SIZE	FSCM NO.
		ISSUED		SCALE	DRG. NO.
					A-2542
				SHEET	1 of 1
				RET.	A